

Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

Claim 1 (currently amended) A method for bonding an integrated circuit device to a glass substrate comprising:

placing a ~~protecting~~ circuit, connecting with an external circuit, on the glass substrate;

providing a melting device with a first laser device and a second laser device;

melting a predetermined portion of the ~~protecting~~ circuit by the first laser device emitting laser light with a relatively short wavelength from a first angle, and then melting a predetermined portion of the glass substrate by the second laser device emitting laser light with a relatively long wavelength from a second angle without the second laser cutting the glass substrate; and

bonding the integrated circuit device on the glass substrate.

Claim 2 (original) The method as claimed in claim 1, wherein the integrated circuit device comprises a driver circuit, a connecting wire, and a main substrate, and the connecting wire is in contact with the predetermined portion, melted by the melting device, of the glass substrate when the integrated circuit device is bonded to the glass substrate.

Claim 3 (currently amended) The method as claimed in claim 4, wherein the connecting wire is bonded to the ~~protecting~~ circuit of the glass substrate via an adhesive and a plurality of conductive particles.

Claim 4 (original) The method as claimed in claim 1, wherein the predetermined portion of the glass substrate is located at edges of the glass substrate.

Claim 5 (new) The method as claimed in claim 1, wherein the melting of the predetermined portion of the glass substrate forms a rounded edge or radius located at an edge of the glass substrate.

Claim 6 (new) A method for bonding an integrated circuit device on a glass substrate, comprising:

- providing a laser melting device;
- emitting a laser beam from the laser melting device;
- melting an edge of the glass substrate without cutting the glass substrate via the laser beam to thereby form a rounded edge or radius at the edge of the glass substrate; and
- adhering the integrated circuit device on the glass substrate.

Claim 7 (new) The method as claimed in claim 6, further comprising a step of:
placing a protecting circuit on the glass substrate.

Claim 8 (new) The method as claimed in claim 7, wherein the integrated circuit device is adhered on the protecting circuit.

Claim 9 (new) The method as claimed in claim 7, wherein the laser melting devices comprises a first laser device and a second laser device.

Claim 10 (new) The method as claimed in claim 9, wherein the first laser device emits a first laser beam at a first angle and the second laser device emits a second laser beam at a second angle.

Claim 11 (new) The method as claimed in claim 10, wherein the first angle is different from the second angle.

Claim 12 (new) The method as claimed in claim 11, wherein the first angle is larger than the second angle.

Claim 13 (new) The method as claimed in claim 9, further comprising steps of:
emitting a short wavelength laser beam from the first laser device; and
eliminating a portion of the protecting circuit at the edge of the glass substrate via the short wavelength laser beam.

Claim 14 (new) The method as claimed in claim 9, further comprising steps of:
emitting a long wavelength laser beam from the second laser device; and
eliminating an edge of the glass substrate via the long wavelength laser beam.

Claim 15 (new) The method as claimed in claim 6, wherein the integrated circuit device having a driving circuit, a connecting wire adhered on the glass substrate, and a main board connecting the connecting wire.

Claim 16 (new) The method as claimed in claim 15, wherein the connecting wire is adhered via an adhesive and a plurality of conductive particles.

Claim 17 (new) The method as claimed in claim 16, wherein the radius at the edge of the glass substrate is between the adhesive and the main board.

Claim 18 (new) The method as claimed in claim 15, wherein the driving circuit is disposed on the main board.

Claim 19 (new) The method as claimed in claim 15, wherein the driving circuit is disposed on the connecting wire.

Claim 20 (new) A method for bonding an integrated circuit device to a glass substrate comprising:

- placing a circuit, connecting with an external circuit, on the glass substrate;
- providing a melting device with a first laser device and a second laser device;
- melting a predetermined portion of the circuit by the first laser device emitting laser light with at a first wavelength from a first angle,
- melting a predetermined portion of the glass substrate by the second laser device emitting laser light with a second wavelength from a second angle without cutting the glass substrate,
- wherein said first wavelength is shorter than said second wavelength; and
- bonding the integrated circuit device on the glass substrate.